

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHENG-YEN TSAI	06/03/2016
HSIN-YI LEE	06/03/2016
CHUNG-CHIANG WU	06/03/2016
DA-YUAN LEE	06/03/2016
WENG CHANG	06/13/2016
MING-HSING TSAI	06/07/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6 SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15192570
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20151083/24061.3257US01
NAME OF SUBMITTER:	JO EL MERCER
SIGNATURE:	/Jo El Mercer/
DATE SIGNED:	06/24/2016

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------------|----|---------------------------------|
| (1) | Cheng-Yen Tsai | of | Hsin-Chu, Taiwan (R.O.C.) |
| (2) | Hsin-Yi Lee | of | Hsinchu City, Taiwan (R.O.C.) |
| (3) | Chung-Chiang Wu | of | Hsin-Chu, Taiwan (R.O.C.) |
| (4) | Da-Yuan Lee | of | Hsinchu County, Taiwan (R.O.C.) |
| (5) | Weng Chang | of | Hsin-Chu, Taiwan (R.O.C.) |
| (6) | Ming-Hsing Tsai | of | Chu-Pei City, Taiwan (R.O.C.) |

have invented certain improvements in

ATOMIC LAYER DEPOSITION METHODS AND STRUCTURES THEREOF

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and filed on and assigned application number ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, **Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC")**, No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Cheng-Yen Tsai

Residence Address: No. 8, Li-Hsin Road 6, Science-Based Industrial Park,
Hsin-Chu 300-77, Taiwan (R.O.C.)

Dated: 06/03/2016

Cheng-Yen Tsai
Inventor Signature

Inventor Name: Hsin-Yi Lee

Residence Address: No.66, Shijie Rd., East Dist., Hsinchu City 30072, Taiwan (R.O.C.)

Dated: 06/03/2016

Hsin-Yi Lee
Inventor Signature

Inventor Name: Chung-Chiang Wu

Residence Address: No. 8, Li-Hsin Road 6, Science-Based Industrial Park,
Hsin-Chu 300-77, Taiwan (R.O.C.)

Dated: 06/03/2016

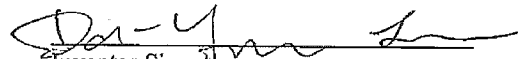
Chung-Chiang Wu
Inventor Signature

Docket No.: TSMC Ref P20151083US00 / 24061.3257US01
Customer No.: 000042717

Inventor Name: Da-Yuan Lee

Residence Address: 10F., No.172, Sec. 2, Jiafong S. Rd., Jhubei City, Hsinchu County 302,
Taiwan (R.O.C.)

Dated: 2016/Jan/03


Inventor Signature

Inventor Name: Weng Chang

Residence Address: N0.20-6F, Lane 79, Hsin-Juang Street, Hsin-Chu 300, Taiwan, (R. O. C.)

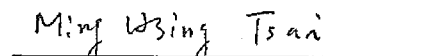
Dated: 6/13, 2016


Inventor Signature

Inventor Name: Ming-Hsing Tsai

Residence Address: 55, Wen-Hsing Rd. 2F, Chu-Pei City, Taiwan, (R.O.C.)
Taiwan

Dated: 6/1/2016


Inventor Signature